Single 2-Input NAND Gate

The MC74HC1G00 is a high speed CMOS 2-input NAND gate fabricated with silicon gate CMOS technology.

The internal circuit is composed of multiple stages, including a buffer output which provides high noise immunity and stable output.

- High Speed: $t_{PD} = 7$ ns (Typ) at $V_{CC} = 5$ V
- Low Power Dissipation: $I_{CC} = 1 \mu A$ (Max) at $T_A = 25$ °C
- High Noise Immunity
- Balanced Propagation Delays (t_{PLH} = t_{PHL})
- Symmetrical Output Impedance $(I_{OH} = I_{OL} = 2 \text{ mA})$
- Chip Complexity: FETs = 40
- Pb-Free Packages are Available

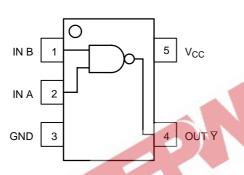


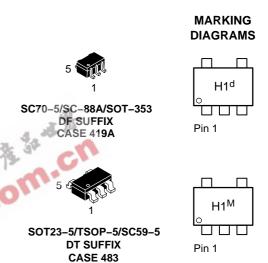
Figure 1. Pinout (Top View)



Figure 2. Logic Symbol



http://onsemi.com



	PIN ASSIGNMENT						
1	IN B						
2	IN A						
3	GND						
4	OUT ₹						
5	V _{CC}						

d = Date Code M = Month Code

Inp	Output	
A	В	Ŧ
L	L	Н
L	Н	Н
Н	L	Н
Н	Н	L

FUNCTION TABLE

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

MAXIMUM RATINGS

Symbol	Parameter		Value	Unit
V _{CC}	DC Supply Voltage		-0.5 to +7.0	V
V _{IN}	DC Input Voltage		-0.5 to $V_{CC} + 0.5$	V
V _{OUT}	DC Output Voltage		-0.5 to $V_{CC} + 0.5$	V
I _{IK}	DC Input Diode Current		±20	mA
I _{OK}	DC Output Diode Current		±20	mA
I _{OUT}	DC Output Sink Current		± 12.5	mA
I _{CC}	DC Supply Current per Supply Pin		±25	mA
T _{STG}	Storage Temperature Range		-65 to +150	°C
TL	Lead Temperature, 1 mm from Case for 10 Seconds		260	°C
TJ	Junction Temperature Under Bias		+ 150	°C
θ_{JA}	Thermal Resistance SC70–5/5	SC-88A (Note 1) TSOP-5	350 230	°C/W
P _D	Power Dissipation in Still Air at 85°C	SC70-5/SC-88A TSOP-5	150 200	mW
MSL	Moisture Sensitivity		Level 1	
F _R	Flammability Rating Oxyger	n Index: 28 to 34	UL 94 V-0 @ 0.125 in	
V _{ESD}	Machine	Model (Note 2) e Model (Note 3) e Model (Note 4)	> 2000 > 200 N/A	V
I _{LATCHUP}	Latchup Performance Above V _{CC} and Below GND at	125°C (Note 5)	±500	mA

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

1. Measured with minimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 2 ounce copper trace with no air flow.

- Tested to EIA/JESD22-A114-A.
- Tested to EIA/JESD22-A115-A.
- Tested to JESD22-C101-A.
- 5. Tested to EIA/JESD78.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit
V _{CC}	DC Supply Voltage	2.0	6.0	V
V _{IN}	DC Input Voltage	0.0	V _{CC}	V
V _{OUT}	DC Output Voltage	0.0	V _{CC}	V
T _A	Operating Temperature Range	- 55	+ 125	°C
t _r , t _f	Input Rise and Fall Time $ \begin{array}{c} V_{CC} = 2.0 \ V \\ V_{CC} = 3.0 \ V \\ V_{CC} = 4.5 \ V \\ V_{CC} = 6.0 \ V \\ \end{array} $	0 0 0 0	1000 600 500 400	ns

DEVICE JUNCTION TEMPERATURE VERSUS TIME TO 0.1% BOND FAILURES

Junction Temperature °C	Time, Hours	Time, Years
80	1,032,200	117.8
90	419,300	47.9
100	178,700	20.4
110	79,600	9.4
120	37,000	4.2
130	17,800	2.0
140	8,900	1.0

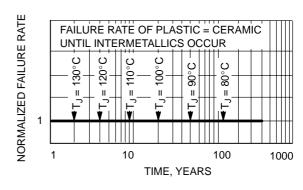


Figure 3. Failure Rate vs. Time Junction Temperature

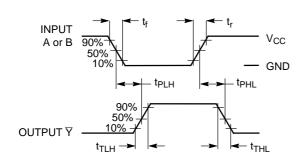
DC ELECTRICAL CHARACTERISTICS

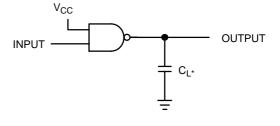
			V _{CC}	1	T _A = 25°C	;	T _A ≤	85°C	-55°C ≤ 1	T _A ≤ 125°C	
Symbol	Parameter	Test Conditions	(V)	Min	Тур	Max	Min	Max	Min	Max	Unit
V _{IH}	Minimum High-Level Input Voltage		2.0 3.0 4.5 6.0	1.5 2.1 3.15 4.20			1.5 2.1 3.15 4.20		1.5 2.1 3.15 4.20		V
V _{IL}	Maximum Low-Level Input Voltage		2.0 3.0 4.5 6.0			0.5 0.9 1.35 1.80		0.5 0.9 1.35 1.80		0.5 0.9 1.35 1.80	V
V _{OH}	Minimum High-Level Output Voltage V _{IN} = V _{IH} or V _{IL}	$V_{IN} = V_{IH} \text{ or } V_{IL}$ $I_{OH} = -20 \mu\text{A}$	2.0 3.0 4.5 6.0	1.9 2.9 4.4 5.9	2.0 3.0 4.5 6.0		1.9 2.9 4.4 5.9		1.9 2.9 4.4 5.9		V
		$V_{IN} = V_{IH} \text{ or } V_{IL}$ $I_{OH} = -2 \text{ mA}$ $I_{OH} = -2.6 \text{ mA}$	4.5 6.0	4.18 5.68	4.31 5.80		4.13 5.63		4.08 5.58		
V _{OL}	Maximum Low-Level Output Voltage V _{IN} = V _{IH} or V _{IL}	$V_{IN} = V_{IH} \text{ or } V_{IL}$ $I_{OL} = 20 \mu\text{A}$	2.0 3.0 4.5 6.0		0.0 0.0 0.0 0.0	0.1 0.1 0.1 0.1	.4	0.1 0.1 0.1 0.1		0.1 0.1 0.1 0.1	V
		$V_{IN} = V_{IH} \text{ or } V_{IL}$ $I_{OL} = 2 \text{ mA}$ $I_{OL} = 2.6 \text{ mA}$	4.5 6.0		0.17 0.18	0.26 0. 2 6		0.33 0.33		0.40 0.40	
I _{IN}	Maximum Input Leakage Current	$V_{IN} = 6.0 \text{ V or GND}$	6.0		3	± 0.1		±1.0		±1.0	μΑ
I _{CC}	Maximum Quiescent Supply Current	$V_{IN} = V_{CC}$ or GND	6.0			1.0		10		40	μΑ

AC ELECTRICAL CHARACTERISTICS (Input $t_{\text{r}} = t_{\text{f}} = 6.0 \text{ ns}$)

			1	T _A = 25°(С	T _A ≤	85°C	-55°C ≤ 1	T _A ≤ 125°C	
Symbol	Parameter	Test Conditions	Min	Тур	Max	Min	Max	Min	Max	Unit
t _{PLH} ,	Maximum	$V_{CC} = 5.0 \text{ V}$ $C_L = 15 \text{ pF}$		3.5	15		20		25	ns
t _{PHL}	Propagation Delay, Input A or B to \overline{Y}	$\begin{array}{c ccccccccccccccccccccccccccccccccccc$		19 10.5 7.5 6.5	100 27 20 17		125 35 25 21		155 90 35 26	
t _{TLH} ,	Output Transition	$V_{CC} = 5.0 \text{ V}$ $C_L = 15 \text{ pF}$		3	10		15		20	ns
t _{THL}	Time	$\begin{array}{c ccccccccccccccccccccccccccccccccccc$		25 16 11 9	125 35 25 21		155 45 31 26		200 60 38 32	
C _{IN}	Maximum Input Capacitance			5	10		10		10	pF
						Туріс	al @ 25°	°C, V _{CC} = 5.0	V	
C _{PD}	Power Dissipation Cap	pacitance (Note 6)					,	10		pF

^{6.} C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: $I_{CC(OPR)} = C_{PD} \bullet V_{CC} \bullet f_{in} + I_{CC}$. C_{PD} is used to determine the no–load dynamic power consumption; $P_D = C_{PD} \bullet V_{CC}^2 \bullet f_{in} + I_{CC} \bullet V_{CC}$.





*Includes all probe and jig capacitance.

A 1-MHz square input wave is recommended for propagation delay tests.

Figure 4. Switching Waveforms

Figure 5. Test Circuit

DEVICE ORDERING INFORMATION

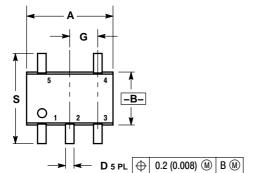
	Device Nomenclature							
Device Order Number	Logic Circuit Indicator	Temp Range Identifier	Technology	Device Function	Package Suffix	Tape and Reel Suffix	Package Type	Tape and Reel Size [†]
MC74HC1G00DFT1	МС	74	HC1G	00	DF	T1 /	SC70-5/SC-88A/ SOT-353	178 mm (7 in) 3000 Unit
MC74HC1G00DFT1G	MC	74	HC1G	00	DF	TiC	SC70-5/SC-88A/ SOT-353 (Pb-Free)	178 mm (7 in) 3000 Unit
MC74HC1G00DFT2	MC	74	HC1G	00	DF	T2	SC70-5/SC-88A/ SOT-353	178 mm (7 in) 3000 Unit
MC74HC1G00DFT2G	MC	74	HC1G	00	DF	T2	SC70-5/SC-88A/ SOT-353 (Pb-Free)	178 mm (7 in) 3000 Unit
MC74HC1G00DTT1	MC	74	HC1G	00	DT	T1	SOT23-5/TSOP-5/ SC59-5	178 mm (7 in) 3000 Unit
MC74HC1G00DTT1G	MC	74	HC1G	00	DT	T1	SOT23-5/TSOP-5/ SC59-5 (Pb-Free)	178 mm (7 in) 3000 Unit

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

PACKAGE DIMENSIONS

SC70-5/SC-88A/SOT-353 **DF SUFFIX**

5-LEAD PACKAGE CASE 419A-02 ISSUE G



- NOTES:

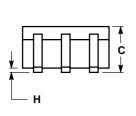
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

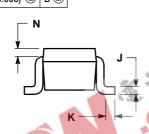
 2. CONTROLLING DIMENSION: INCH.

 3. 419A-01 OBSOLETE. NEW STANDARD 419A-02.

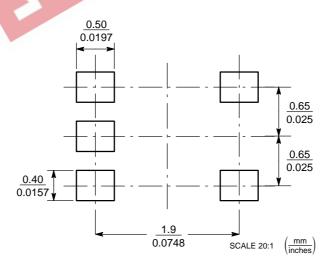
 4. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

	INC	HES	MILLIM	ETERS
DIM	MIN	MAX	MIN	MAX
Α	0.071	0.087	1.80	2.20
В	0.045	0.053	1.15	1.35
С	0.031	0.043	0.80	1.10
D	0.004	0.012	0.10	0.30
G	0.026	BSC	0.65	BSC
Н		0.004		0.10
J	0.004	0.010	0.10	0.25
K	0.004	0.012	0.10	0.30
N	0.008	REF	0.20	REF
S	0.079	0.087	2.00	2.20





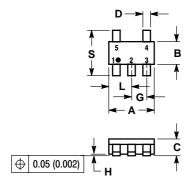
SOLDERING FOOTPRINT*



*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

SOT23-5/TSOP-5/SC59-5 **DT SUFFIX**

5-LEAD PACKAGE CASE 483-02 **ISSUE C**





NOTES

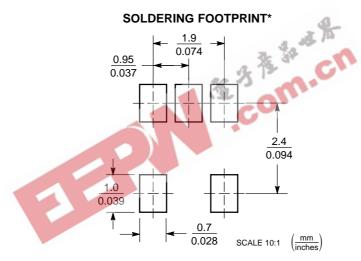
- NOTES:

 1. DIMENSIONING AND TOLERANCING PER
 ANSI Y14.5M, 1982.

 2. CONTROLLING DIMENSION: MILLIMETER.

 3. MAXIMUM LEAD THICKNESS INCLUDES
 LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
 A AND B DIMENSIONS DO NOT INCLUDE
- MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

	MILLIN	IETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	2.90	3.10	0.1142	0.1220
В	1.30	1.70	0.0512	0.0669
С	0.90	1.10	0.0354	0.0433
D	0.25	0.50	0.0098	0.0197
G	0.85	1.05	0.0335	0.0413
Н	0.013	0.100	0.0005	0.0040
J	0.10	0.26	0.0040	0.0102
K	0.20	0.60	0.0079	0.0236
L	1.25	1.55	0.0493	0.0610
М	0	10	0	10
S	2.50	3.00	0.0985	0.1181



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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